

WHAT IS CLAIMED IS:

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1. A liquid-crystal display unit
comprising:

a first board having a signal line, a
scanning line and a pixel electrode;

10 a second board having a common electrode,
the second board opposing said first board;

a liquid-crystal layer provided between
said first board and said second board; and

15 a third board having at least one of a
signal-line driver driving said signal line and a
scanning-line driver driving said scanning line, the
third board being separate from said first board and
said second board.

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2. The liquid-crystal display unit as
claimed in claim 1, wherein said third board is
25 formed of a same material as said first board.

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3. The liquid-crystal display unit as
claimed in claim 1, wherein said third board is
connected to said first board by a flexible cable.

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4. The liquid-crystal display unit as

claimed in claim 1, wherein said third board is connected to said first board by a wire bonding.

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5. The liquid-crystal display unit as claimed in claim 1, wherein said third board is connected to said first board by a flip-chip bonding.

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6. A method of manufacturing a liquid-crystal display unit including: a first board having a signal line, a scanning line and a pixel electrode; a second board having a common electrode, the second board opposing said first board; and a liquid-crystal layer provided between said first board and said second board, the method comprising the steps of:

forming said signal line, said scanning line, said pixel electrode, and at least one of a signal-line driver driving said signal line and a scanning-line driver driving said scanning line on a same substrate; and

dividing said same substrate into said first board and a third board having at least one of said signal-line driver and said scanning-line driver.

7. The method as claimed in claim 6, wherein said step of forming forms said signal line, said scanning line, said pixel electrode, and at

least one of said signal-line driver and said scanning-line driver in a same process.

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8. The method as claimed in claim 6, further comprising the step of connecting said third board to said first board by a flexible cable.

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9. The method as claimed in claim 6, further comprising the step of connecting said third board to said first board by a wire bonding.

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10. The method as claimed in claim 6, further comprising the step of connecting said third board to said first board by a flip-chip bonding.